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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Kazuto NISHIDA

Docket No. 00177/526327

Serial No. 09/331,763

Group Art Unit 3727

Filed June 25, 1999

Examiner J. Merek

METHOD AND APPARATUS FOR  
MOUNTING ELECTRONIC COMPONENT  
ON CIRCUIT BOARD

Amdt

# 11/C

8/15/01

B. Ross

AMENDMENT

Assistant Commissioner for Patents,  
Washington, D.C.

Sir:

In response to the Office Action of February 14, 2001, the period for response to which having been extended by three months to August 14, 2001, kindly amend the above-referenced U.S. patent application as follows:

IN THE SPECIFICATION

Please amend the specification as follows:

Please replace the paragraph beginning at page 29, line 7, to page 30, line 2, with the following rewritten paragraph:

C1  
In this case, the circuit board 4 is provided by a glass cloth base epoxy copper clad laminate board (glass epoxy board), a glass cloth base polyimide resin copper clad laminate board, or the like. These boards 4 have warp and undulation due to thermal hysteresis, cutting, and processing, meaning that their surfaces are not completely flat surfaces. Therefore, as shown

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